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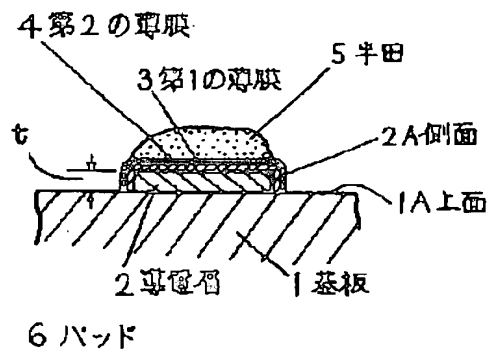
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INT.CL. : H05K 3/24 H05K 3/34

TITLE : FORMING METHOD FOR PAD



ABSTRACT : PURPOSE: To form a stable pad and to improve reliability by laminating a first thin film and a second thin film on a conductive layer formed on a substrate, and fusion-bonding solder on the upper layer of the second film.

CONSTITUTION: A first thin film 3 of nickel plating is so laminated as to cover a conductive layer 2 having a thickness (t) to be formed in a predetermined shape on the surface 1A of a substrate 1, and a second thin film 4 is further so laminated by gold plating as to cover the film 3 to form a pad 6. Solder 5 to be fusion-bonded on the pad 6 is secured on the upper layer 4A of the film 4 so that the layer 2 is not brought into direct contact with the solder 5.

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